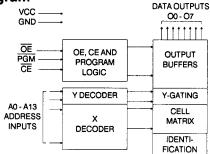
### **Features**

- Low Power CMOS Operation 100 μA max. Standby 30 mA max. Active at 5 MHz
- Fast Read Access Time 120ns
- Wide Selection of JEDEC Standard Packages Including OTP 28-Lead 600 mil Cerdip and OTP Plastic DIP 32-Pad OTP PLCC
- 5V± 10% Supply
- High Reliability CMOS Technology 2000V ESD Protection
- Fast Programming 4ms/byte (typical)
- Two-line Control
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Commercial and Industrial Temperature Ranges

### **Block Diagram**



### **Description**

The AT27C128 chip is a low-power, high performance 131,072 bit Ultraviolet Erasable and Electrically Programmable Read Only Memory (EPROM) organized 16K x 8. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 120ns, eliminating the need for speed reducing WAIT states on high performance microprocessor systems.

Atmel's 1.5 micron CMOS technology provides optimum speed, low power and high noise immunity. Power consumption is typically only 10mA in Active Mode and less than  $10\mu$  A in Standby. In addition to the speed, power and reliability advantages of the CMOS process, the CMOS technology is an extension of Atmel's high quality and highly manufacturable floating poly EPROM technology.

## **Pin Configurations**

Pin Name	Function
A0-A13	Addresses
O0-O7	Outputs
CE	Chip Enable
ŌĒ	Output Enable
PGM	Program Strobe
NC	No Connect

A12 U U U U U U U U U U U U U U U U U U U	1 2 3 4 5 6 7 8 9 10 11 12 13 14	28 27 26 25 24 23 22 21 20 19 18 17 16 15	VCC PGM A13 A8 A9 A11 OE A10 OE O7 O6 O5 O4 O3	i	444444

A7 VPP VCC A13 A12 NC PGM  A6 3 2 1323139 A8 8 28 A9 A4 7 27 A11 A5 8 28 A9 A4 10 24 A0 A6 11 22 C7 C0 13 15 17 19 21 O6 C1 NC O4 O1 GND O3 O5
--

Note: PLCC package Pins 1 and 17 are DON'T CONNECT

128K (16K x 8) UV Erasable CMOS EPROM

4





### **Description** (Continued)

The AT27C128 comes in a choice of industry standard JEDEC-approved packages including; 32-pin DIP in ceramic or one time programmable (OTP) plastic, and 32-pin OTP plastic J-leaded chip carrier (PLCC). All devices feature two line control ( $\overline{CE}$ ,  $\overline{OE}$ ) to give designers the flexibility to prevent bus contention.

With high density 16K byte storage capability, the AT27C128 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's 27C128 has additional features to ensure high quality and efficient production use. The Fast Programming Algorithm reduces the time required to program the part and guarantees reliable programming. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages.

### **Erasure Characteristics**

The entire memory array of the AT27C128 is erased (all outputs read as V<sub>OH</sub>) after exposure to ultraviolet light at a wavelength of 2537Å. Complete erasure is assured after a minimum of 20 minutes exposure using 12,000 µW/cm² intensity lamps spaced one inch away from the chip. Minimum erase time for lamps at other intensity ratings can be calculated from the minimum integrated erasure dose of 15W sec/cm². To prevent unintentional erasure, an opaque label is recommended to cover the clear window on any UV erasable EPROM which will be subjected to continuous fluorescent indoor lighting or sunlight.

### **Absolute Maximum Ratings\***

Temperature Under Bias	40°C to +85°C
Storage Temperature	65°C to +125°C
Voltage on Any Pin with Respect to Ground	2.0V to +7.0V <sup>(1)</sup>
Voltage on A9 with Respect to Ground	2.0V to +14.0V <sup>(1)</sup>
VPP Supply Voltage with Respect to Ground	2.0V to +14.0V <sup>(1)</sup>
Integrated UV Erase Dose	7258 w• sec/cm <sup>2</sup>

\*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### Notes

 Minimum voltage is -0.6V dc which may undershoot to -2.0V for pulses of less than 20ns. Maximum output pin voltage is V<sub>CC</sub>+0.75V dc which may overshoot to +7.0V for pulses of less than 20ns.

## Operating Modes

MODE \ PIN	CE	ŌĒ	PGM	Ai	V <sub>PP</sub>	Vcc	Outputs
Read	VIL	VIL	ViH	Ai	X <sup>(1)</sup>	Vcc	Dout
Output Disable	VIL	VIH	ViH	X	Х	Vcc	High Z
Standby	VıH	Х	Х	Х	X <sup>(5)</sup>	Vcc	High Z
Fast Program <sup>(2)</sup>	VIL	ViH	VIL	Ai	Vpp	Vcc	Din
PGM Verify	VIL	VIL	VIH	Ai	$V_{PP}$	Vcc	Dout
PGM Inhibit	ViH	Х	Х	Х	V <sub>PP</sub>	Vcc	High Z
Product Identification <sup>(4)</sup>	VIL	V <sub>I</sub> L	Х	A9 = V <sub>H</sub> <sup>(3)</sup> A0 = V <sub>IH</sub> or V <sub>IL</sub> A1-A13 = V <sub>IL</sub>	Vcc	Vcc	Identification Code

Notes: 1. X can be VIL or VIH.

- 2. Refer to Programming Characteristics.
- 3.  $V_H = 12.0 \pm 0.5 V$ .
- Two identifier bytes may be selected. All Ai inputs are held low (V<sub>II.</sub>), except A9 which is set to V<sub>H</sub>
- and A0 which is toggled low  $(V_{IL})$  to select the Manufacturer's Identification byte and high  $(V_{IH})$  to select the Device Code Byte.
- Standby V<sub>CC</sub> current (I<sub>SB</sub>) is specified with V<sub>PP</sub>=V<sub>CC</sub>. V<sub>CC</sub> > V<sub>PP</sub> will cause a slight increase in I<sub>SB</sub>.

### 4

## D.C. and A.C. Operating Conditions for Read Operation

		AT27C128						
		-12	-15	-20	-25			
Operating Temperature	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C			
(Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C			
V <sub>CC</sub> Power Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%			

## D.C. and Operating Characteristics for Read Operation

Symbol	Parameter	Condition		Min	Max	Units
I <sub>LI</sub>	Input Load Current	$V_{IN} = -0.1V$ to $V_{CC} + 1V$			10	μΑ
ILO	Output Leakage Current	$V_{OUT} = -0.1V$ to $V_{CC} + 0.1V$	*****		10	μΑ
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	Vpp = 3.8 to Vcc + 0.3V			10	μΑ
		I <sub>SB1</sub> (CMOS)	Com.		100	μΑ
IsB	SB VCC (1) Standby Current	$\overline{CE} = V_{CC}-0.3$ to $V_{CC} + 1.0V$	Ind.,Mil.		200	μΑ
TSB VCC Standsy Same	100 olanosy carrent	$\frac{I_{SB2} \text{ (TTL)}}{CE} = 2.0 \text{ to V}_{CC} + 1.0 \text{V}$	Com.		2	mA
			Ind.,Mil.		3	mA
Icc	Vcc Active Current	f=5MHz,lout=0mA,	Com.		30	mA
100	ACC Active Content	CE = VIL	Ind.,Mil.		40	mA
VIL	Input Low Voltage			-0.6	0.8	٧
ViH	Input High Voltage			2.0	Vcc+1	٧
Vol	Output Low Voltage	I <sub>OL</sub> = 2.1mA			.45	V
		I <sub>OH</sub> = -100μ A		Vcc-0.3		٧
Vон	Output High Voltage	I <sub>OH</sub> = -2.5mA		3.5		٧
		I <sub>OH</sub> = -400μ A		2.4		V

Notes: 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$ , and removed simultaneously or after  $V_{PP}$ .

# A.C. Characteristics for Read Operation

				AT27C128								
				-	12	-	15	-	20	-:	25	
Symbol	Parameter	Condition		Min	Max	Min	Max	Min	Max	Min	Max	Units
tacc (4)	Address to	$\overline{CE} = \overline{OE}$	Com.		120		150		200		250	ns
	Output Delay	$=V_{IL}$	Ind.		120		150		200		250	ns
t <sub>CE</sub> (3)	CE to Output Delay	$\overline{OE} = V_{IL}$			120		150		200		250	ns
toe (3,4)	OE to Output Delay	CE = V <sub>IL</sub>			60		70		75		100	ns
t <sub>DF</sub> <sup>(2,5)</sup>	OE or CE High to Output Float	Œ = V <sub>t</sub> ∟			50		50		55		60	ns
tон	Output Hold from Address, CE or OE, whichever occurred first	CE = OE = VIL			0		0		0		0	ns

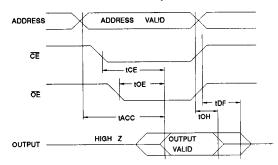
Notes: 2, 3, 4, 5. - see AC Waveforms for Read Operation.



<sup>2.</sup> V<sub>PP</sub> may be connected directly to V<sub>CC</sub>, except during programming. The supply current would then be the sum of  $I_{CC}$  and  $I_{PP}$ .



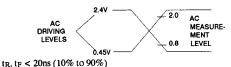
# A.C. Waveforms for Read Operation (1)



#### Notes

- Timing measurement references are 0.8V and 2.0V. Input AC driving levels are 0.45V and 2.4V, unless otherwise specified.
- tpr is specified from OE or CE, whichever occurs first. Output float is defined as the point when data is no longer driven.
- OE may be delayed up to tCE-tOE after the falling edge of CE without impact on tCE.
- OE may be delayed up to tACC-tOE after the address is valid without impact on tACC.
- This parameter is only sampled and is not 100% tested.

# Input Test Waveforms and Measurement Levels



### **Output Test Load**



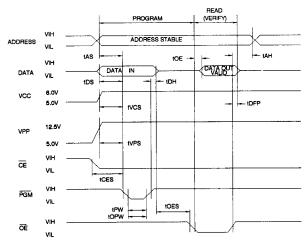
Note:  $C_L=100pF$  including jig capacitance.

## Pin Capacitance (f=1MHz T=25°C) (1)

	Тур	Max	Units	Conditions	
CiN	4	6	pF	V <sub>IN</sub> = 0V	
Соит	8	12	pF	V <sub>OUT</sub> = 0V	

Notes: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

# Programming Waveforms (1)



### Notes:

- 1. The Input Timing Reference is 0.8V for  $V_{IL}$  and 2.0V for  $V_{IH}$ .
- toE and tDFP are characteristics of the device but must be accommodated by the programmer.
- When programming the AT27C128 a 0.1μF capacitor is required across V<sub>PP</sub> and ground to suppress spurious voltage transients.

### 4

### **D.C. Programming Characteristics**

 $T_A = 25 \pm 5^{\circ}C$ ,  $V_{CC} = 6.0 \pm 0.25V$ ,  $V_{PP} = 12.5 \pm 0.5V$ 

Sym-		Test	Li	mits	
bol	Parameter	Conditions	Min	Max	Units
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		10	μΑ
VIL	Input Low Level	(All Inputs)	-0.6	8.0	٧
ViH	Input High Level		2.0	V <sub>CC+</sub> 1	٧
VOL	Output Low Volt.	I <sub>OL</sub> = 2.1mA		.45	٧
Vон	Output High Volt.	I <sub>OH</sub> = -400μA	2.4		٧
ICC2	Vcc Supply Curren (Program and Veri			30	mA
IPP2	V <sub>PP</sub> Current	CE = V <sub>IL</sub>		25	mA
VID	A9 Product Iden- tification Voltage		11.5	12.5	٧

### A.C. Programming Characteristics

 $T_A=25\pm5^{\circ}C$ ,  $V_{CC}=6.0\pm0.25V$ ,  $V_{PP}=12.5\pm0.5V$ 

C		Test		mits	
Sym- bol	Parameter	Conditions* (see Note 1)	Min		Units
tas	Address Setup Tir	ne	2		μS
tces	CE Setup Time		2		μS
toes	OE Setup Time		2		μS
tos	Data Setup Time		2		μS
taH	Address Hold Tim	е	0		μS
ton	Data Hold Time		2		μS
tDFP	OE High to Output Float Delay	(Note 2)	0	130	ns
tvps	V <sub>PP</sub> Setup Time		2		μS
tvcs	Vcc Setup Time		2		μS
tpw	PGM Initial Pro- gram Pulse Width	(Note 3)	0.95	1.05	ms
topw	PGM Overprogram Pulse Width	(Note 4)	2.85	78.75	ms
toe	Data Valid from O	Ē		150	ns

### \*A.C. Conditions of Test:

Input Rise and Fall Times (10% to 90%)	20ns
Input Pulse Levels	0.45V to 2.4V
Input Timing Reference Level	. $0.8V$ to $2.0V$
Output Timing Reference Level	. $0.8V\ to\ 2.0V$

### Notes:

- V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
- This parameter is only sampled and is not 100% tested.
   Output Float is defined as the point where data is no longer driven see timing diagram.
- 3. Initial Program Pulse width tolerance is 1msec±5%.
- 4. The length of the overprogram pulse may vary from 2.85 msec to 78.75 msec as a function of the iteration counter value X.

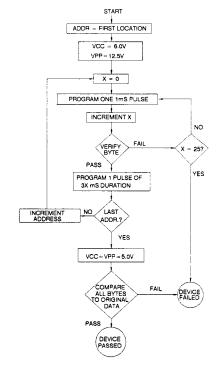
# Atmel's 27C128 Integrated Product Identification Code:

		Pins					Hex			
Codes	AO	07	O6	O5	04	Оз	02	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	1	1F
Device Type	1	1	0	0	0	0	0	1	1	83

### **Fast Programming Algorithm**

Two  $\overline{PGM}$  pulse widths are used to program; initial and overprogram. At are set to address the desired byte.  $V_{CC}$  is raised to 6.0V. The first  $\overline{PGM}$  pulse is 1ms. The programmed byte is then verified. If the byte programmed successfully, then an overprogram  $\overline{PGM}$  pulse is applied for 3ms. If the byte fails to program after the first 1ms pulse, then up to 25 successive 1ms pulses are applied with a verification after each pulse. When the byte passes verification, the overprogram pulse width is 3X (times) the number of 1ms pulses required earlier (75ms max).

If the part fails to verify after 25 1ms pulses have been applied, it is considered as failed. After the first byte is programmed, the Ai are set to the next address repeating the algorithm until all required addresses are programmed. Then  $V_{\rm CC}$  is lowered to 5.0V. All bytes subsequently are read to compare with the original data to determine if the device passes or fails.







# Ordering Information

tacc	Icc (mA)		Ordering Code	Package	Operation Range	
(ns)	Active	Standby	Ordering Code	Fackage	Operation hange	
120	30	0.1	AT27C128-12DC	28DW6	Commercial (0°C to 70°C)	
120	40	0.2	AT27C128-12DI	28DW6	Industrial (-40°C to 85°C)	
150	30	0.1	AT27C128-15DC AT27C128-15PC AT27C128-15JC	28DW6 28P6 32J	Commercial (0°C to 70°C)	
150	40	0.2	AT27C128-15DI AT27C128-15PI AT27C128-15JI	28DW6 28P6 32J	Industrial (-40°C to 85°C)	
200	30	0.1	AT27C128-20DC AT27C128-20PC AT27C128-20JC	28DW6 28P6 32J	Commercial (0°C to 70°C)	
200	40	0.2	AT27C128-20DI AT27C128-20PI AT27C128-20JI	28DW6 28P6 32J	Industrial (-40°C to 85°C)	
250	30	0.1	AT27C128-25DC AT27C128-25PC AT27C128-25JC	28DW6 28P6 32J	Commercial (0°C to 70°C)	
250	40	0.2	AT27C128-25DI AT27C128-25PI AT27C128-25JI	28DW6 28P6 32J	Industrial (-40°C to 85°C)	

Package Type				
28DW6	28 Lead, 0.600" Wide, Windowed, Ceramic Dual Inline Package (Cerdip)			
32J	32 Lead, Plastic J-Leaded Chip Carrier OTP (PLCC)			
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package OTP (PDIP)			